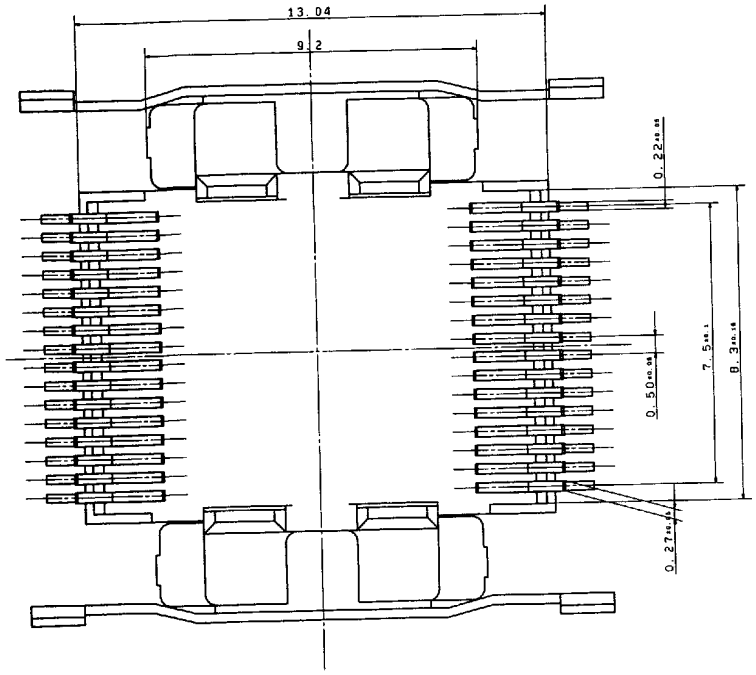
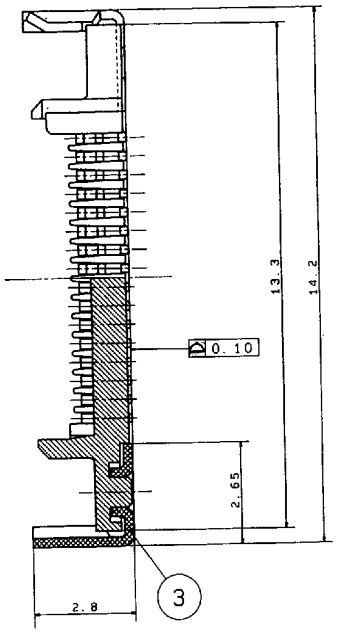
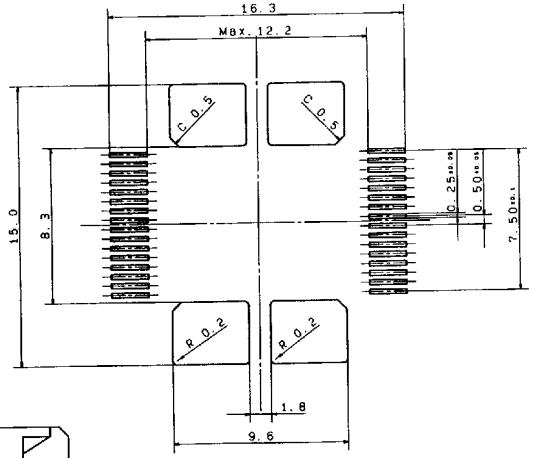
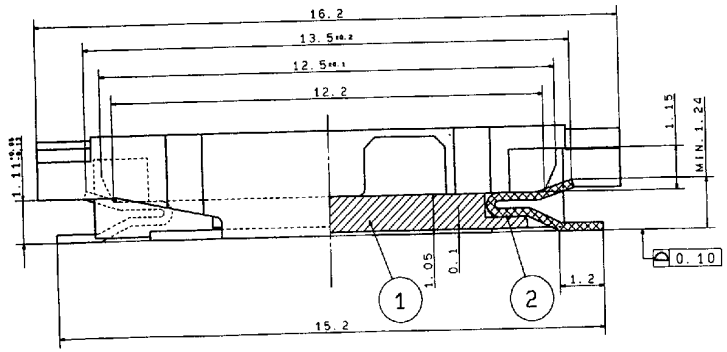


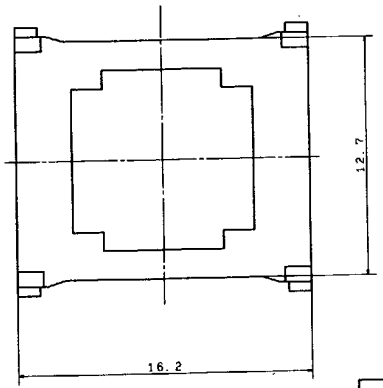


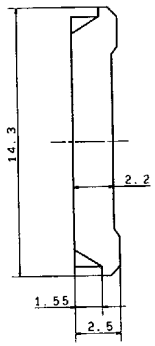
TSOP — 32 50 XX — SMT — TT

- Number of Contacts: 32
- 50 = .50mm Lead Spacing
- XX: Blank = Standard Pack (5 parts/pack); TP = Tape & Reel (body only); *Frames are packaged in vinyl bags
- Plating



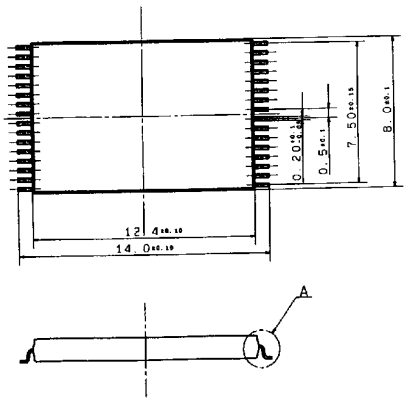




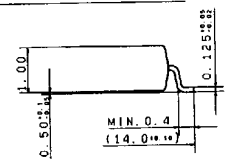


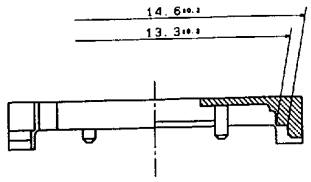
ALL DIMENSIONS IN MILLIMETERS

± 0.3 General Tolerance



Detail "A" (S=10:1)





1 = Body
2 = Contact
3 = Frame Holder

Robinson Nugent
812/945-0211
812/945-0805 FAX

TSOP-3250XX-SMT-TT
32 position,SMT TSOP Socket (.50mm lead spacing)
Body and Frame

Specifications for TSOP Sockets

MATERIALS

Body: Liquid crystal polymer
Frame: Glass-filled PPS
Contact: Copper alloy
Holder: Copper alloy
Flammability: UL 94V-0

Plating: TT = 2.03 µm (80 µinch) Tin/Lead overall.
1.27 µm (50 µinch) Nickel underplate.

MECHANICAL

Electrical Shock Resistance: 490m/s^2 (50G) resistance
Mechanical Shock Resistance: 981m/s^2 (100 G)
Vibration Resistance: 20 to 55Hz, 98m/s^2 (100G)

ELECTRICAL

Current Rating: 0.1 Ampere per contact
Insulation: 1000 MΩ minimum
Dielectric Withstanding: 500 Volts AC for 1 minute
Contact Resistance: 60 mΩ Maximum

ENVIRONMENTAL

Operating Temperature: -55°C to + 65°C

Thermal Shock Resistance:
Contact Resistance: Maximum 60mΩ
Insulation Resistance: Minimum 100MΩ

Heat Resistance:
Contact Resistance: Maximum 60mΩ
Insulation Resistance: Minimum 100MΩ

Humidity Resistance:
Contact Resistance: Maximum 60mΩ
Insulation Resistance: Minimum 100MΩ

H_2S Gas Resistance:
Contact Resistance: Maximum 60mΩ

SO_2 Gas Resistance:
Contact Resistance: Maximum 60mΩ

Soldering Heat Resistance: Peak temperature of 245°C
300°C within 2 seconds

Cream Solder Printing: Screen thickness - 0.15mm

APPLICABLE IC

28 contacts:	Mitsubishi: 28P2C-A Fujitsu: FPT-28P-M03
32 contacts:	Okidenki: TSOP-814-K, TSOP32P-814-L Hitachi: TFP-32DA, TFP-32DAR
40 contacts:	Mitsubishi: 40P3J

SOCKETS